

ABSTRACT OF THE DISCLOSURE

A semiconductor device includes a semiconductor construction assembly having a semiconductor substrate which has first and second surfaces, and has an
5 integrated circuit element formed on the first surface, a plurality of connection pads which are connected to the integrated circuit element, a protective layer which covers the semiconductor substrate and has openings for exposing the connection pads, and
10 conductors which are connected to the connection pads, arranged on the protective layer, and have pads. An upper insulating layer covers the entire upper surface of the semiconductor construction assembly including the conductors except the pads. A sealing
15 member covers at least one side surface of the semiconductor construction assembly. An upper conductor is formed on the upper insulating layer, and has one end electrically connected to the pads and an external connection pad, respectively, an external
20 connection pad of at least one of the upper conductors being disposed in a region corresponding to the sealing member.